

S55	79	("20010033478" "20020017699" "4774630" "4827376" "5148265" "5148266" "5285352" "5438305" "5486720" "5491302" "5518964" "5530288" "5536909" "5557501" "5576680" "5608262" "5633785" "5642261" "5659952" "5677569" "5679977" "5688716" "5706174" "5717245" "5747870" "5766987" "5787581" "5798286" "5821609" "5830782" "5869887" "5869894" "5886393" "5892417" "5905639" "5913109" "5915752" "5918112" "5929517" "5973391" "5976913" "6005466" "6037659" "6046076" "6049972" "6054756" "6075289" "6081035" "6093888" "6104272" "6124546" "6133626" "6156980" "6165814" "6169328" "6181015" "6194774" "6218729" "6228686" "6229200" "6238949" "6238950" "6249039" "6252778" "6255714" "6281570" "6292086" "6310386" "6323735" "6326696" "6329715" "6344688" "6362525" "6377464" "6387747" "6492201" "6498099" "6521987" "6583513").PN. OR ("6856007").URPN.	US-PGPUB; OR USPAT; USOCR	OFF	2005/06/06 11:54
S56	7	(solder adj1 mask adj1 (trench or recess or cavity)) and ((circuit adj1 board) or (substrate))	US-PGPUB; OR USPAT; EPO; JPO; DERWENT; IBM_TDB	OFF	2005/06/06 11:58
S57	2	(solder adj1 mask adj1 (trench or recess or cavity)) and (surface adj1 acoustic adj1 wave)	US-PGPUB; OR USPAT; EPO; JPO; DERWENT; IBM_TDB	OFF	2005/06/06 11:59
S58	1	(solder adj1 mask adj1 (trench or recess or cavity)) and (surface adj1 mount adj1 device)	US-PGPUB; OR USPAT; EPO; JPO; DERWENT; IBM_TDB	OFF	2005/06/06 12:00
S59	3	(solder adj1 mask adj1 (trench or recess or cavity)) and (surface adj1 mount)	US-PGPUB; OR USPAT; EPO; JPO; DERWENT; IBM_TDB	OFF	2005/06/06 12:01

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S48	70	("4683394" "4734608" "4736128" "4737742" "4795934" "5202652" "5237235" "5281883").PN. OR ("5459368").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:21
S49	51	("3657610" "4191905" "4266156" "4405875" "4604644" "4661192" "4699682" "4734608" "4736128" "4737742" "4864470" "4993000" "5014111" "5090119" "5095240" "5120678" "5252882" "5281883" "5359494" "5390401" "5438305" "5459368" "5471722" "5504980" "5900581").PN. OR ("5969461").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:30
S50	19	("4737742" "4864470" "5214308").PN. OR ("5471722").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:43
S51	6	("5946195" "5969461" "6002592" "6566601" "6753595" "6831234").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:46
S52	6981	(mold\$2 or encapsula\$4) and (substrate or board) and SAW	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:48
S53	729	(mold\$2 or encapsula\$4) and (substrate or board) and (surface adj1 acoustic adj1 wave)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:49
S54	7	(mold\$2 or encapsula\$4) and (substrate or board) and (surface adj1 acoustic adj1 wave) and(solder adj1 mask)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 11:49

S60	5	(solder adj1 mask adj1 (trench or recess or cavity)) and (chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:02
S61	7	(solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:02